



## Material Content Data Sheet



<b>Sales Product Name</b>		BSL606SN H6327		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000906354						
<b>Package</b>		PG-TSOP6-6-6		<b>Weight*</b>		13.57 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.006	0.04		433	
	noble metal	gold	7440-57-5	0.023	0.17		1678	
	inorganic material	silicon	7440-21-3	0.347	2.56	2.77	25597	27708
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		435	
	non noble metal	chromium	7440-47-3	0.018	0.13		1306	
	non noble metal	copper	7440-50-8	5.882	43.34	43.52	433401	435229
wire	non noble metal	copper	7440-50-8	0.047	0.35	0.35	3499	3499
encapsulation	organic material	carbon black	1333-86-4	0.068	0.50		4983	
	plastics	epoxy resin	-	1.454	10.71		107129	
	inorganic material	silicondioxide	60676-86-0	5.241	38.62	49.83	386163	498275
leadfinish	non noble metal	tin	7440-31-5	0.303	2.23	2.23	22299	22299
plating	noble metal	silver	7440-22-4	0.176	1.30	1.30	12990	12990
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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